

# RAKE Correlator

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# Overview

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Why should you care?

Channel Model

What is it? How does it work?

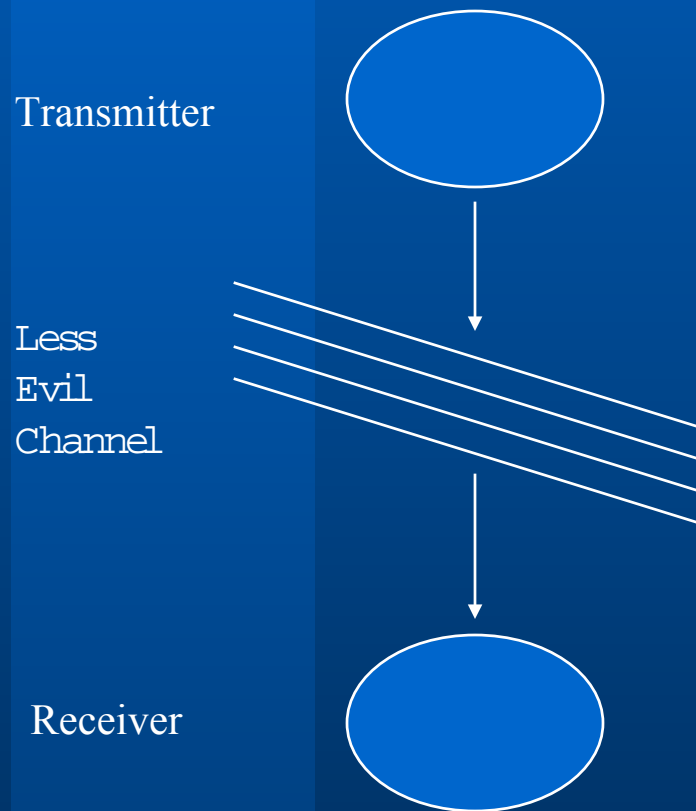
Our RAKE finger Specs

# Why should you care?

- **Wireless Devices**
  - DSP
  - Vocoder
  - RAKE Correlator

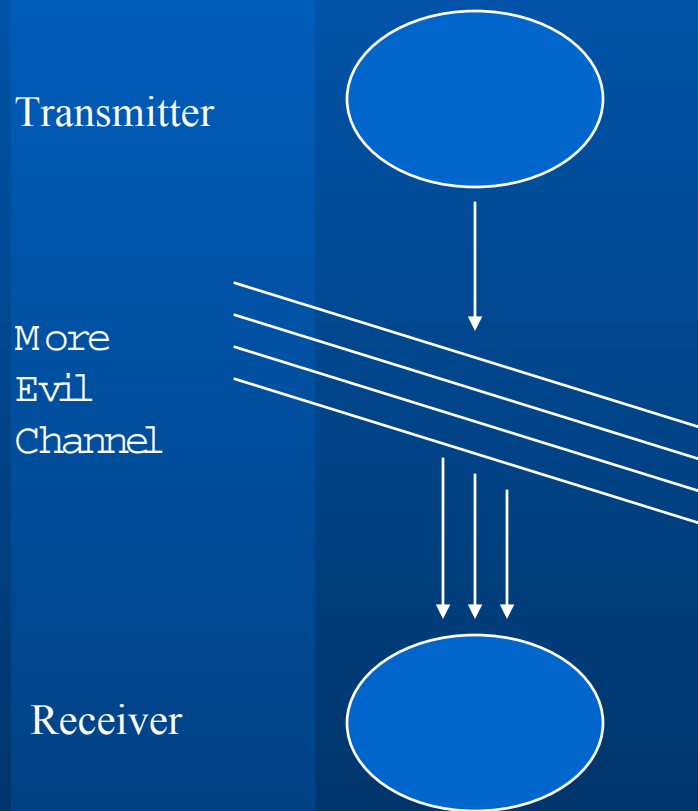


# Channel Model



- **Standard, Basic Channel Model**
  - Additive noise
  - Amplitude Changes
  - Phase Changes

# Channel Model

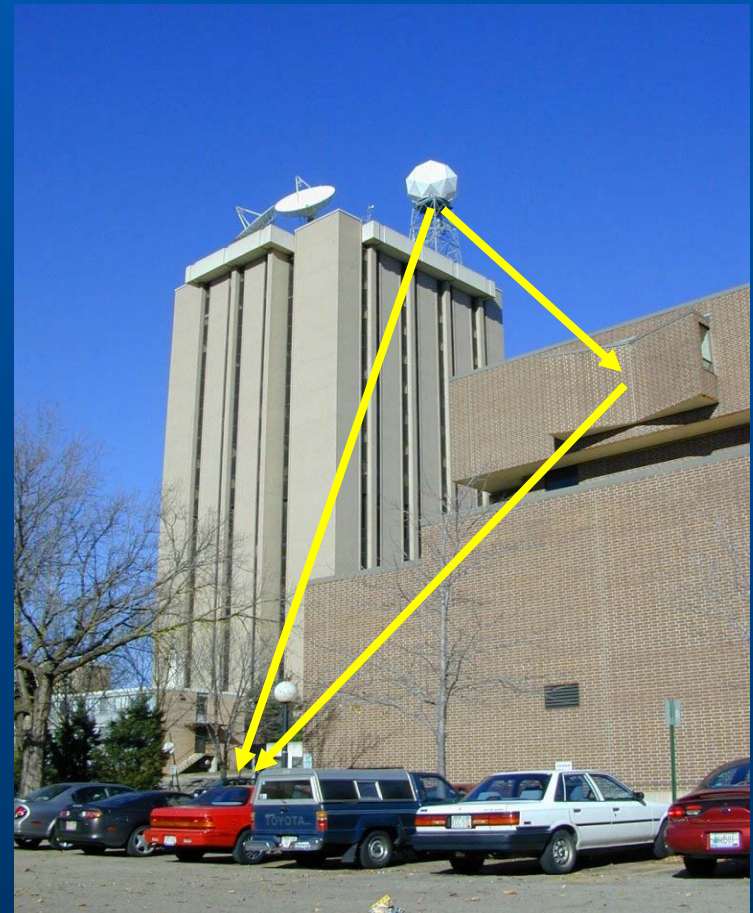


- **More “realistic” channel model**
  - Additive noise
  - Multiple Paths
    - Amplitude Changes
    - Phase Changes
  - Added Together at receiver

# Channel Model

- **Reasons**

- Signals bounce off buildings
- Amplitude, phase distortion
- Delayed paths summed with direct path



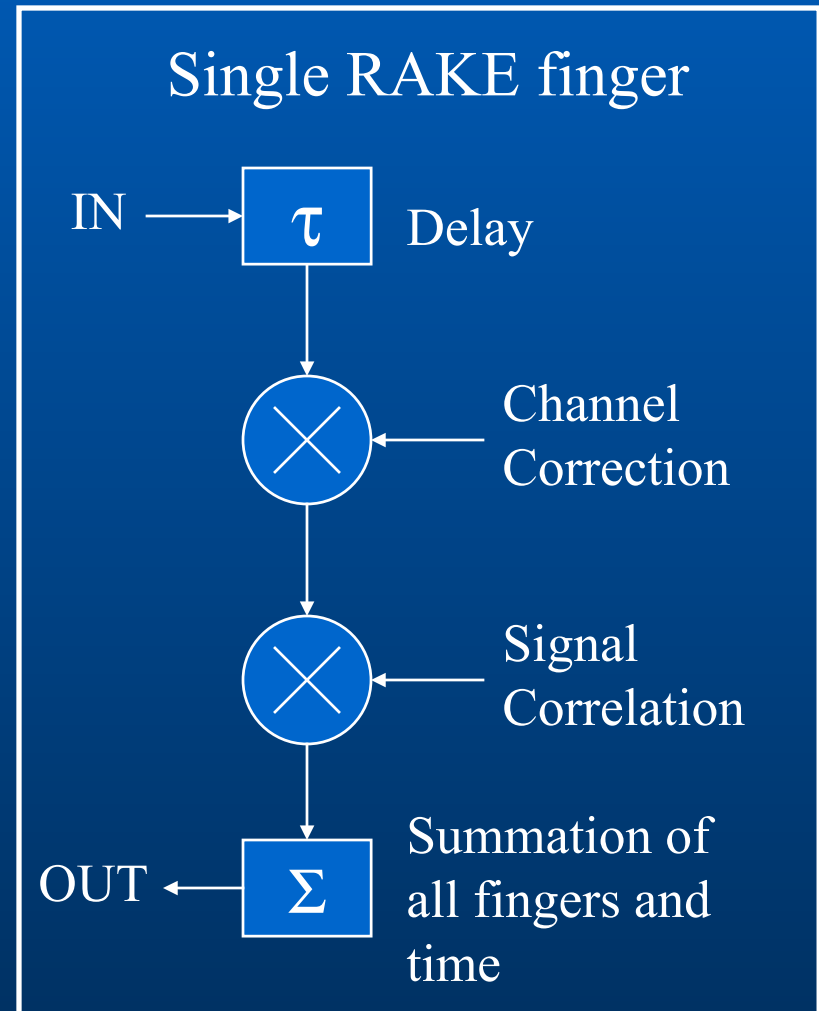
# What is it? How does it work?

**RAKE = Matched Filter for Channel Model**

- **RAKE Correlator**
  - Multiple paths increase performance
  - Acts like a set of mini-correlators, called **RAKE fingers**
  - Each finger is delayed and scaled for a given path (ie. A reflection from a building)

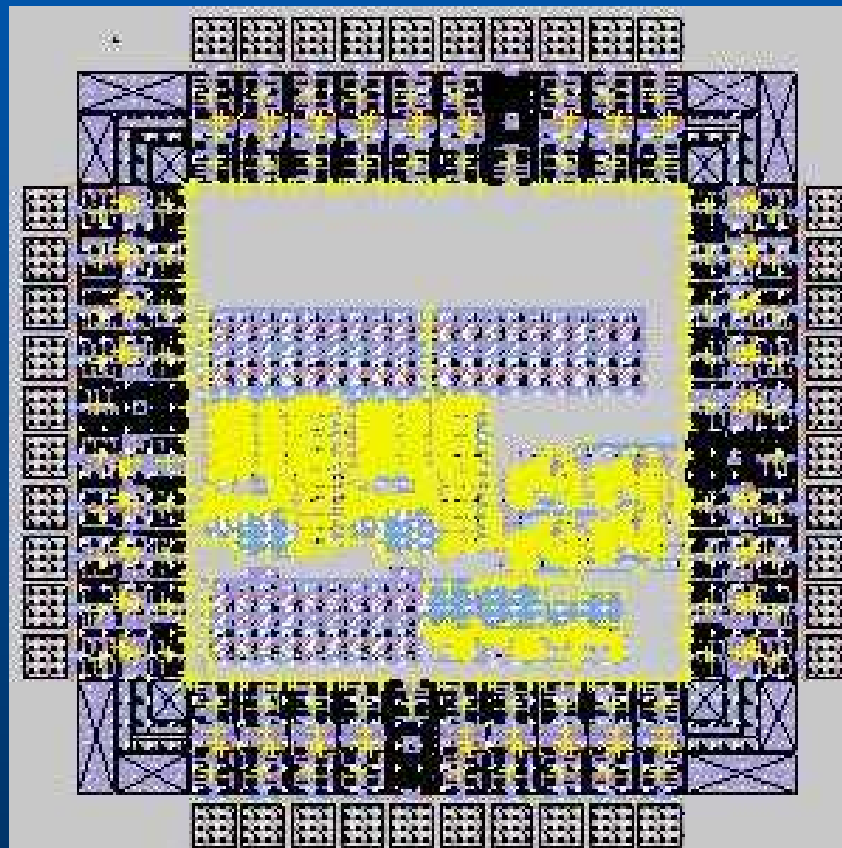
# Our specs

- Up to 8 RAKE fingers, Max delay of 16 chips
- 4 bit, 2's complement
- 32 chips/symbol, 1 bit/symbol
- Assume no inter-signal interference





# Full Chip



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# Basic Floorplan

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4x32 Signal  
Latch Array

4x8  
Delay  
Latch  
Array

4x8  
Channel  
Latch  
Array

×

4 bit  
Multiplier

×

4 bit  
Multiplier

+

16 bit  
Adder

4x16 Input  
SR Array

Control PLAs

# Arithmetic

4x32 Signal  
Latch Array

4x8  
Delay  
Latch  
Array

4x8  
Channel  
Latch  
Array

×

4 bit  
Multiplier

×

4 bit  
Multiplier

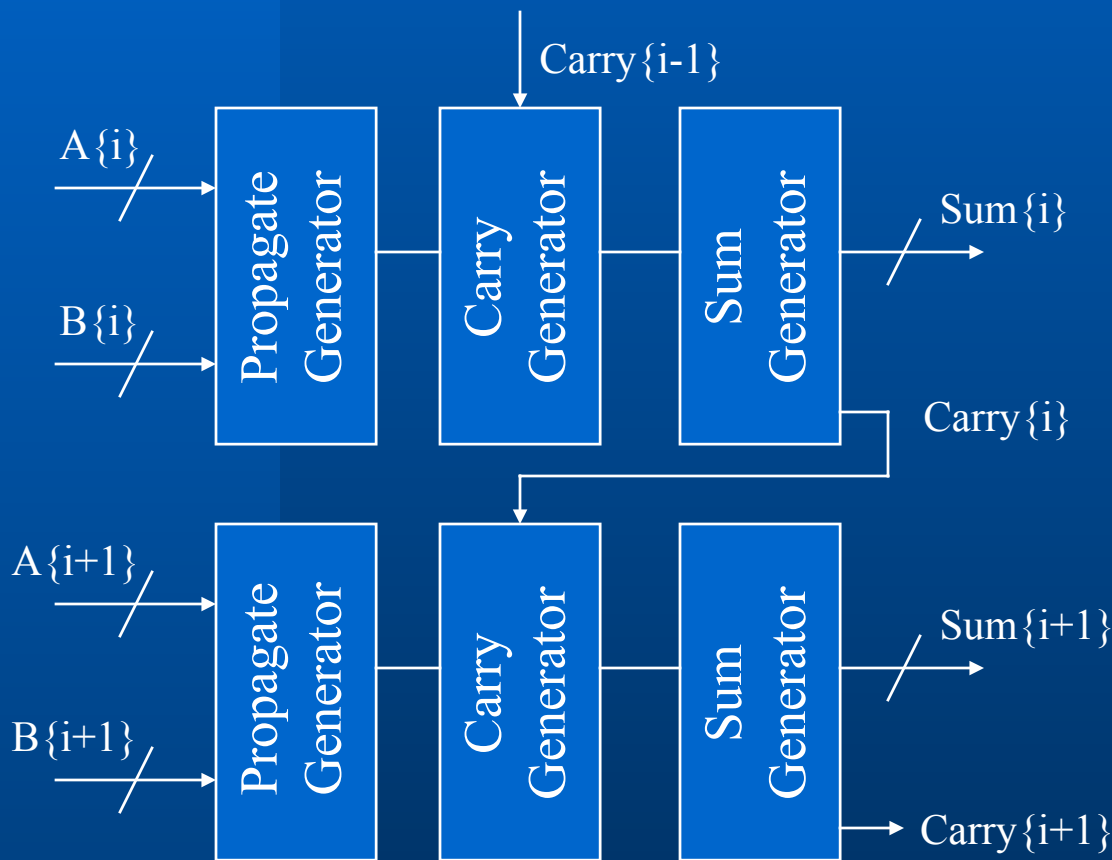
+

16 bit  
Adder

4x16 Input  
SR Array

Control PLAs

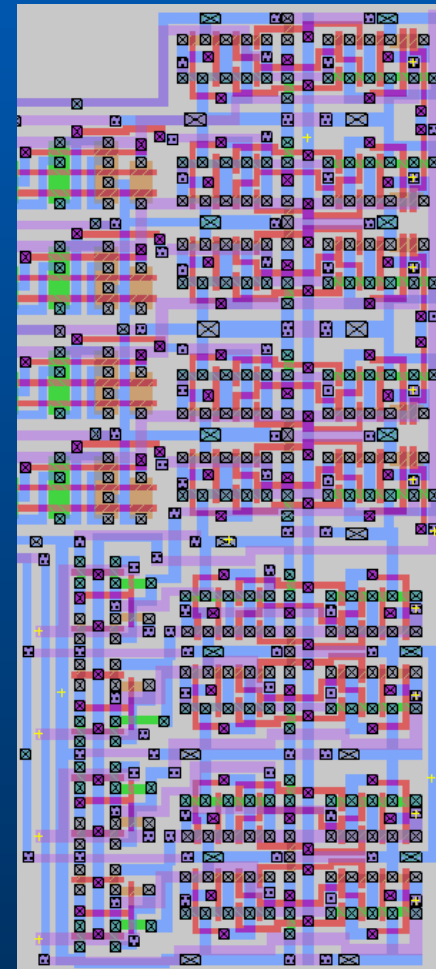
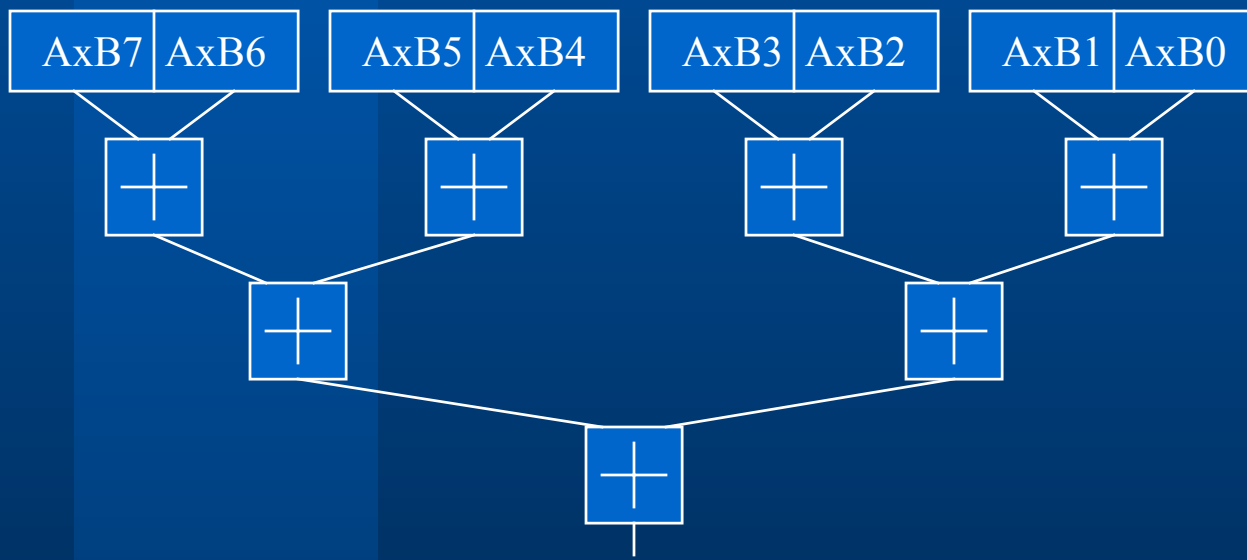
# Carry Look-ahead Adder



- Carry Look-Ahead is 3x faster than ripple carry
- Carry Eqns
  - $Carry\{i\} = G\{i\} + P\{i\} \cdot C\{i-1\}$
  - $G\{i\} = A\{i\} \cdot B\{i\}$
  - $P\{i\} = A\{i\} + B\{i\}$
- Used in Multiplier and Summation blocks

# Multiplier

- 1st Multiplier with a Manchester Adder and rounding of bits
- 2nd Multiplier with a CLA



# Control

4x32 Signal  
Latch Array

4x8  
Delay  
Latch  
Array

4x8  
Channel  
Latch  
Array

×

4 bit  
Multiplier

×

4 bit  
Multiplier

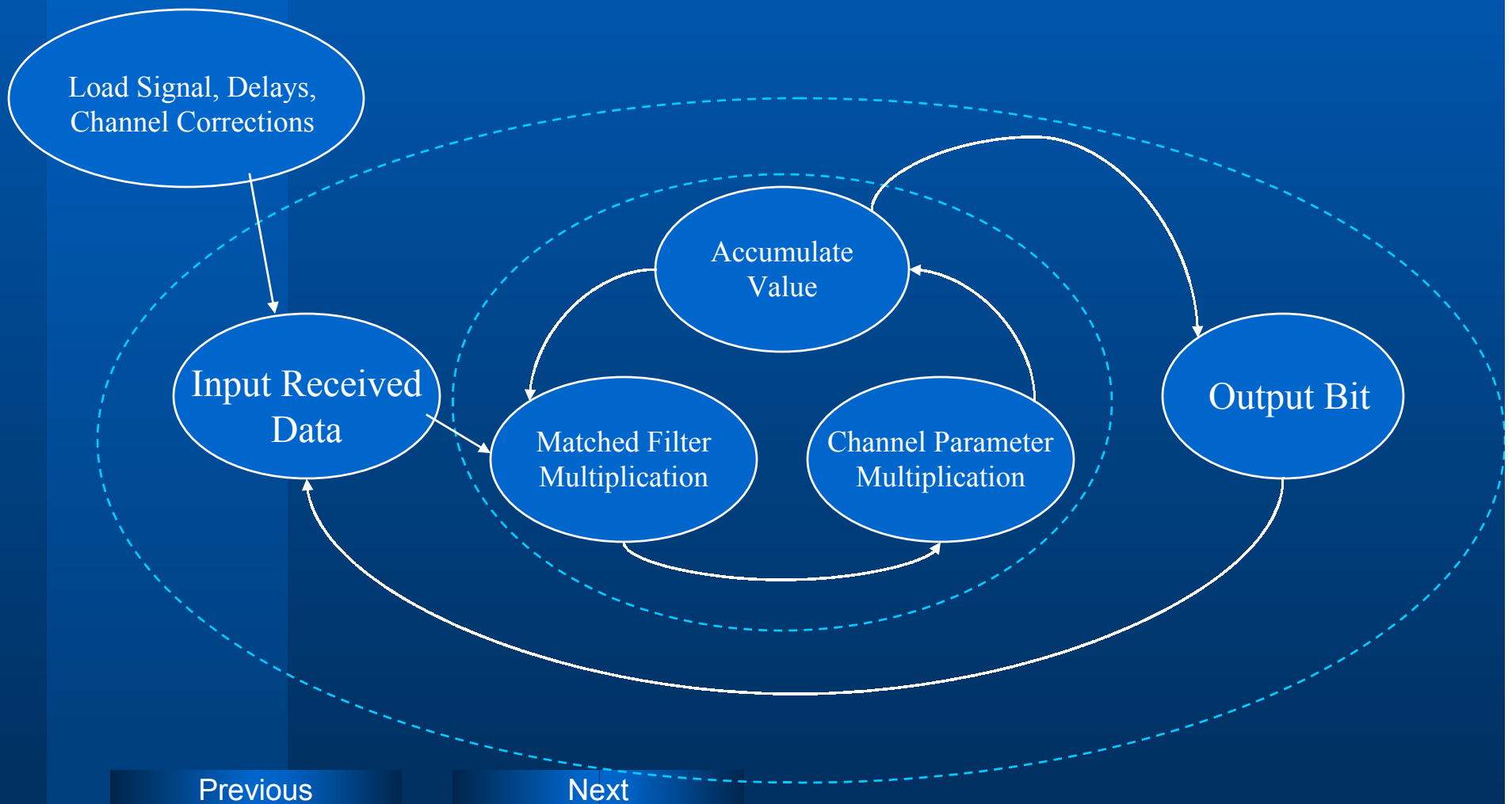
+

16 bit  
Adder

4x16 Input  
SR Array

Control PLAs

# Control



# Timing Control

## Major Points

- Followed 2-phase clocking discipline
  - Internal outputs all latched to clock B
  - Internal Inputs all latched to clock A

## Speed Optimizations

- Split up main PLA into 4 sub PLAs
- Always full pipeline
- .5  $\mu$ M process
- Carry Lookahead Adders
- Fast Tree Multipliers



# Memory

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4x32 Signal  
Latch Array

4x8  
Delay  
Latch  
Array

4x8  
Channel  
Latch  
Array

×

4 bit  
Multiplier

×

4 bit  
Multiplier

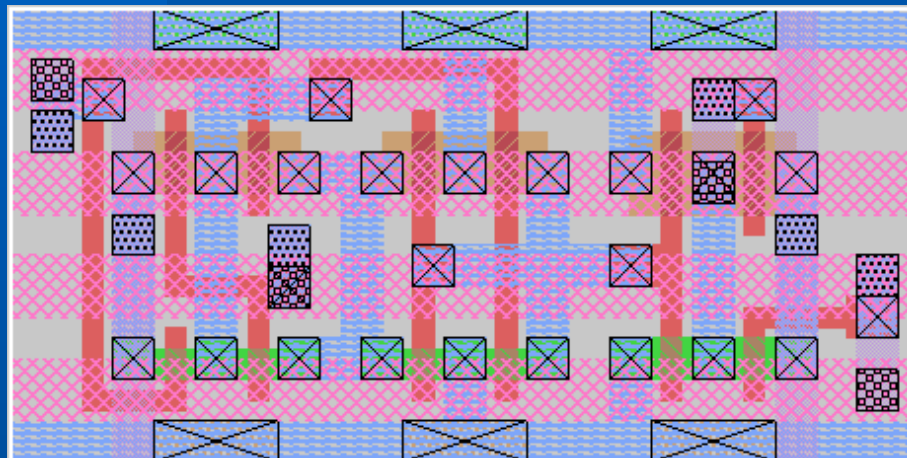
+

16 bit  
Adder

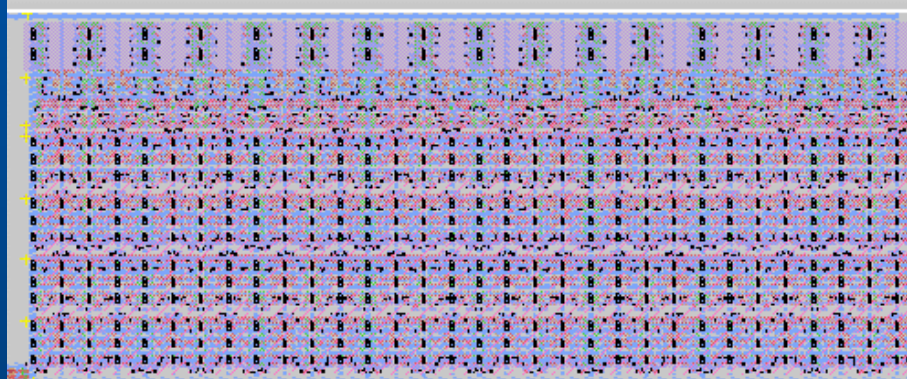
4x16 Input  
SR Array

Control PLAs

# Memory Layout



Basic Latch Cell



Latch Array

# Memory Subcells

4x32 Signal  
Latch Array

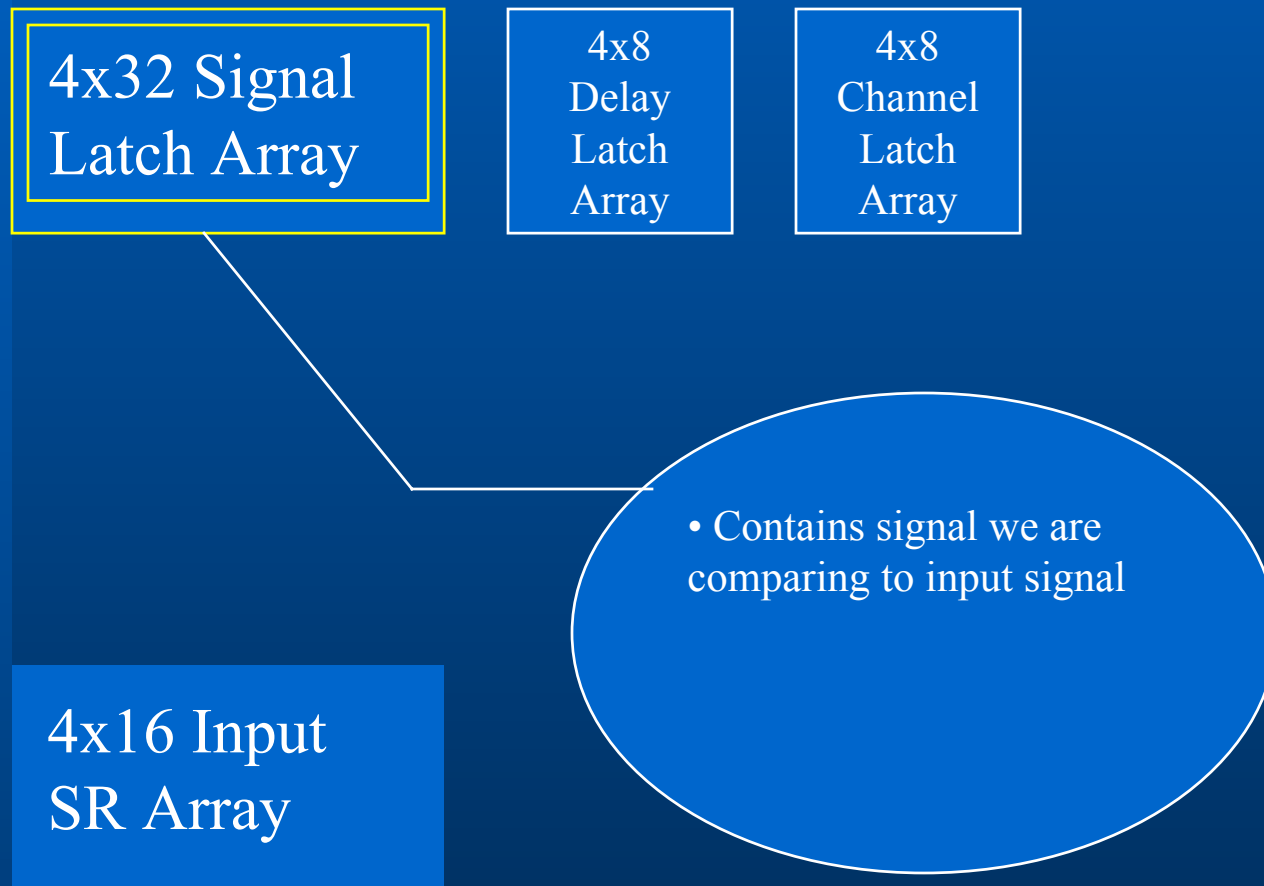
4x8  
Delay  
Latch  
Array

4x8  
Channel  
Latch  
Array

4x16 Input  
SR Array

- Contains received data
- Shifts in new data

# Memory Subcells



# Memory Subcells

4x32 Signal  
Latch Array

4x8  
Delay  
Latch  
Array

4x8  
Channel  
Latch  
Array

4x16 Input  
SR Array

- Contains amount of time to delay for each “finger”
- Up to 8 fingers

# Memory Subcells

4x32 Signal  
Latch Array

4x8  
Delay  
Latch  
Array

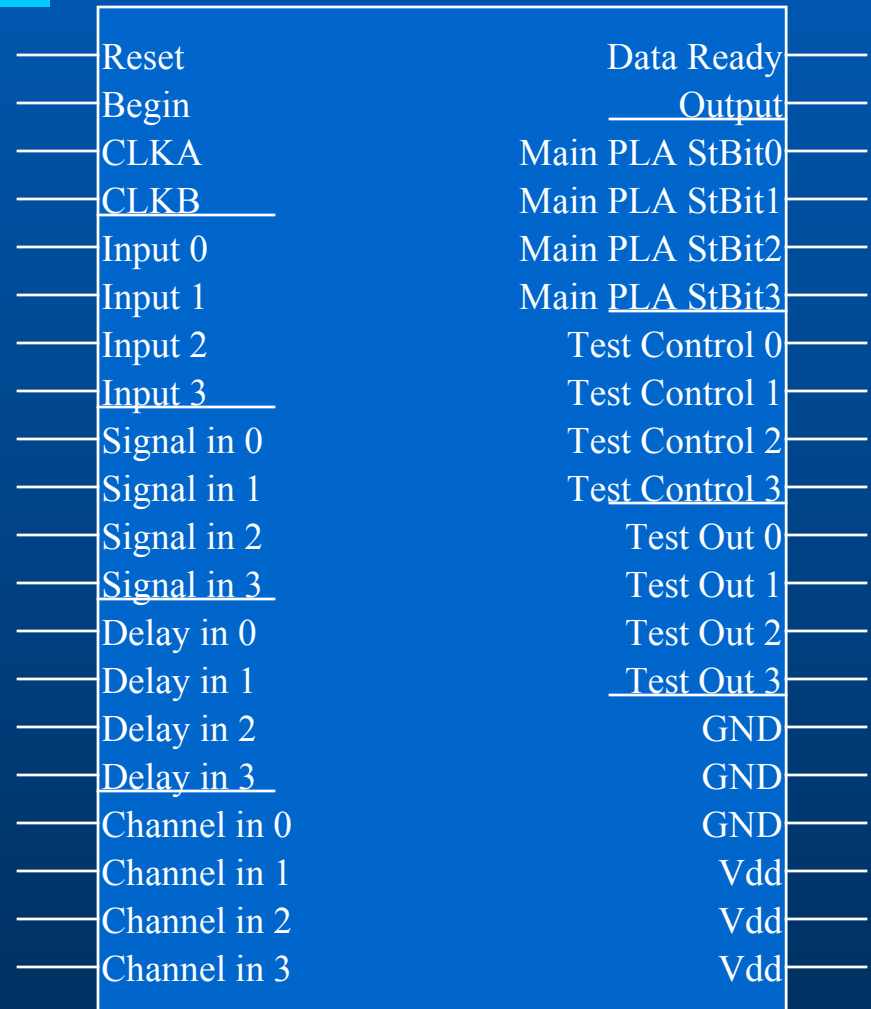
4x8  
Channel  
Latch  
Array

4x16 Input  
SR Array

- Contains data to reverse effects of channel for each “finger” or delay path

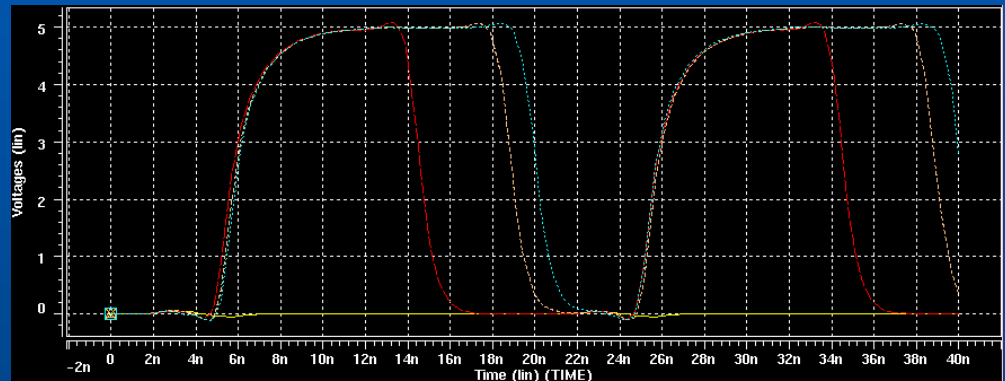
# Testability

- “Test Control” chooses what appears on “Test Out”
- Final output is a 0 or 1, on “Output” pin
- Main PLA state bits are outputs

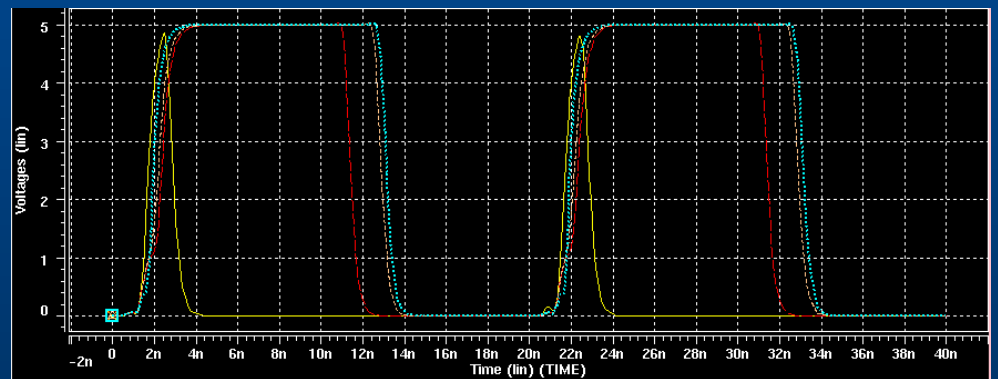


# Spice Analysis

**Multiplier plots**  
~8 ns



**4 bit adder plots**  
~2.2 ns





# Performance Summary

## Max Delay Paths

- 15.5 ns longest path in PLA
- 8 ns multiplier
- 2.2 ns four bit CLA (8 ns 16 bit adder)

## Theoretical Maxima

- Clock ~ 50 MHz
- Input ~ 6.4 Mchips/sec
- Output ~ 200 kbits/sec

# Current Status

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- **Integrating and fitting components into pad frame**
- **High level Integration testing**
- **Developing test strategies**

# Future...



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